■ Notice (Soldering and Mounting)

- 1. Soldering Conditions
- (1) Reflow

One heat stress, shown in the profile at right, is applied to the resonator, then after being placed in natural conditions for 1 hour, the resonator is measured.

- (a) Pre-heating conditions should be +150 to +180°C for 60 to 120 seconds. Ascending time up +150°C should be longer than 30 seconds.
- (b) Heating conditions should be within 40 seconds at +230°C min., but peak temperature should be lower than +260°C.

(2) Soldering Iron

Components shall be measured after soldering on PCB at $+350\pm5^{\circ}$ C for 3.0 ± 0.5 seconds and leaving in natural condition for 24 hours. The soldering iron shall not touch the components while soldering.

2. Wash

(1) Cleaning Solvents

HCFC, Isopropanol, Tap water, Demineralized water, Cleanthrough750H, Pine alpha 100S, Techno care FRW

(2) Temperature Difference : dT *1

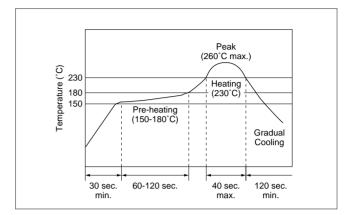
dT≦60°C (dT=Component-solvent)

- *1 ex. In case the component at +90°C immerses into cleaning solvent at +60°C, then dT=30°C.
- (3) Conditions
 - (a) Ultrasonic Wash
 1 minute max. in above solvent at +60°C max.
 (Frequency: 28kHz, Output: 20W/l)

(4) Drying

5 minutes max. by air blow at +80°C max.

- (5) Others
 - (a) Total washing time should be within 10 minutes.
 - (b) The component may be damaged if it is washed with chlorine, petroleum, or alkali cleaning solvent.
- 3. Notice for Mounting
 - (a) Please ensure the component is thoroughly evaluated in your application circuit.
 - (b) Please do not apply excessive mechanical stress to the component and lead terminals during soldering.



(b) Immersion Wash

5 minutes max. in above solvent at +60°C max.

- (c) Shower or Rinse Wash5 minutes max. in above solvent at +60°C max.
- (c) Ultrasonic cleaning of the component is acceptable. However, the size of bath, size and thickness of PCB should be evaluated to confirm stable electrical characteristics are maintained.
- (c) In the case of the bulk component, dry heating treatment (130°C. for 5 hours min.) is required before reflow soldering. Then, the component should be soldered within 48 hours after dry heating treatment. Continued on the following page.



Continued from the preceding page.

■ Notice (Storage and Operating Condition)

Product Storage Condition
 Please store the products in a room where the temperature/humidity is stable, and avoid such places where there are large temperature changes.
 Please store the products under the following conditions:

Temperature: -10 to + 40 degrees C Humidity: 15 to 85% R.H.

2. Expiration Date on Storage

Expiration date (Shelf life) of the products is six months after delivery under the conditions of a sealed and unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because the products may be degraded in solderability and/or rusty.

Please confirm solderability and characteristics for the products regularly.

- 3. Notice on Product Storage
- Please do not store the products in a chemical atmosphere (Acids, Alkali, Bases, Organic gas, Sulfides and so on), because the characteristics may be reduced in quality, and/or be degraded in the solderability due to the storage in a chemical atmosphere.

■ Notice (Rating)

The component may be damaged if excessive mechanical stress is applied.

■ Notice (Handling)

The component may stop oscillating or oscillate irregularly under improper circuit conditions.

- (2) Please do not put the products directly on the floor without anything under them to avoid damp and/or dusty places.
- (3) Please do not store the products in places such as: in a damp heated place, in a place where direct sunlight comes in, in a place applying vibrations.
- (4) Please use the products immediately after the package is opened, because the characteristics may be reduced in quality, and/or be degraded in the solderability due to storage under the poor conditions.
- (5) Please do not drop the products to avoid cracking of ceramic elements.
- 4. Others

Conformal coating of the component is acceptable. However, the resin material, curing temperature, and other process conditions should be evaluated to confirm that stable electrical characteristics are maintained.

Please be sure to consult with our sales representatives or engineers whenever and prior to using the products.

